

PAT-NO: JP409025469A  
DOCUMENT- JP 09025469 A  
IDENTIFIER:  
TITLE: THERMOSETTING RESIN COMPOSITION, CURING  
METHOD, WOODY MATERIAL AND MOLDED ARTICLE

PUBN-DATE: January 28, 1997

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APPL-NO: JP07195870  
APPL-DATE: July 7, 1995

INT-CL C09J161/06 , C08J009/04 , D04H001/04 ,  
(IPC): D06M015/41 , D21H019/24

ABSTRACT:

PROBLEM TO BE SOLVED: To obtain the subject composition having long pot-life and excellent low-temperature curability and workability, giving a cured product having excellent strength, water resistance, oil resistance and weather resistance and useful as a molding material for building material, etc., by using a mixture of a specific

curing agent and a precondensate of a phenolic compound and an aldehyde as a main component.

SOLUTION: This resin composition is composed mainly of a mixture of (A) a precondensate of a monohydric or a polyhydric phenol and an aldehyde (e.g. phenol-formaldehyde precondensate or phenol-resorcinol-formaldehyde precondensate) and (B) a uronic compound such as a compound of the formula (R is an alkylene or an arylene). Preferably, a sulfomethyl group or a sulfimethyl group is introduced into the component A.

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